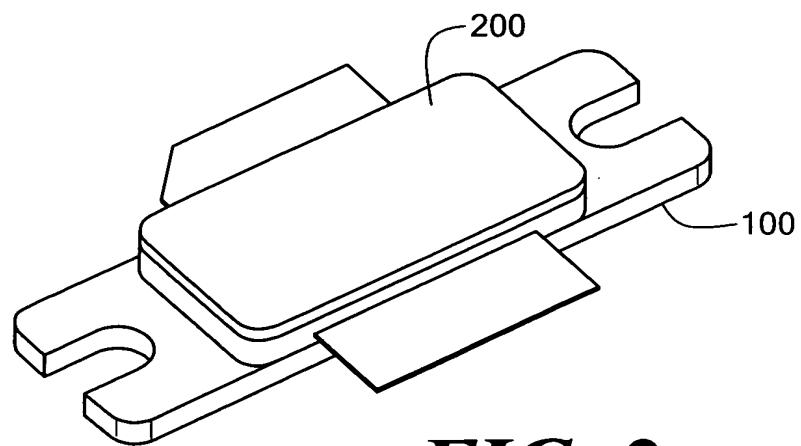
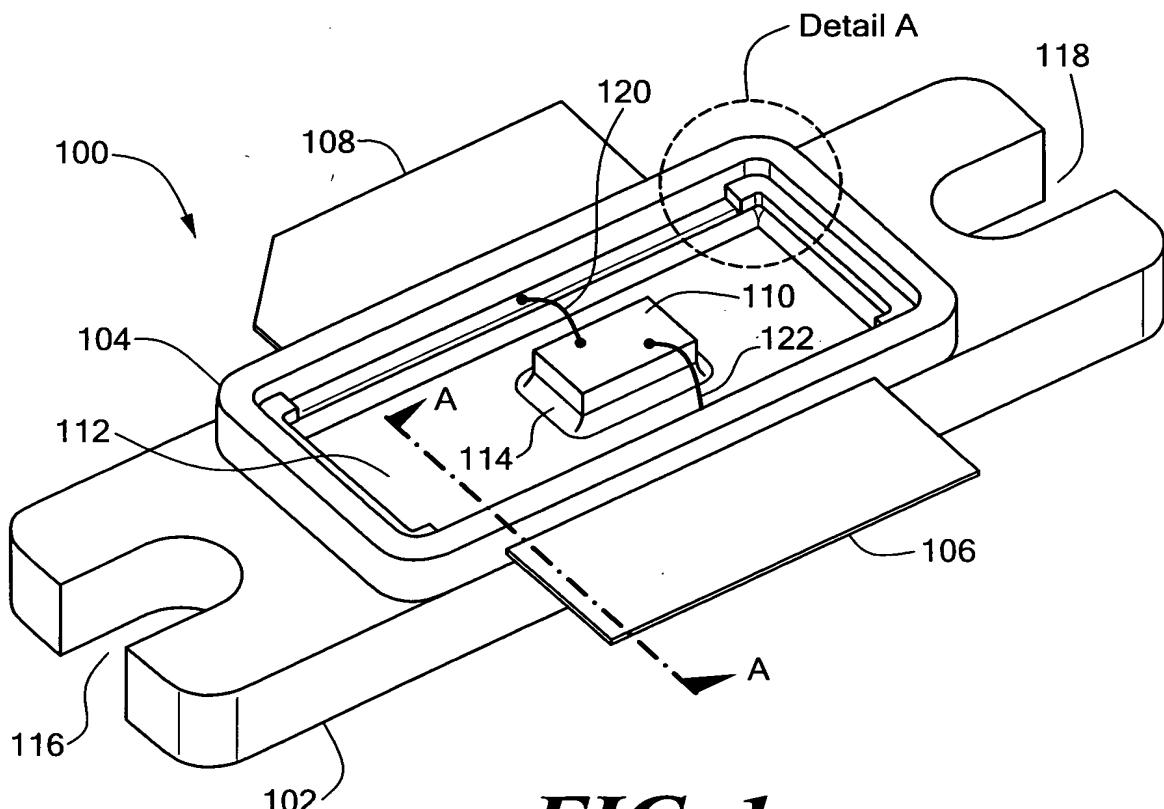


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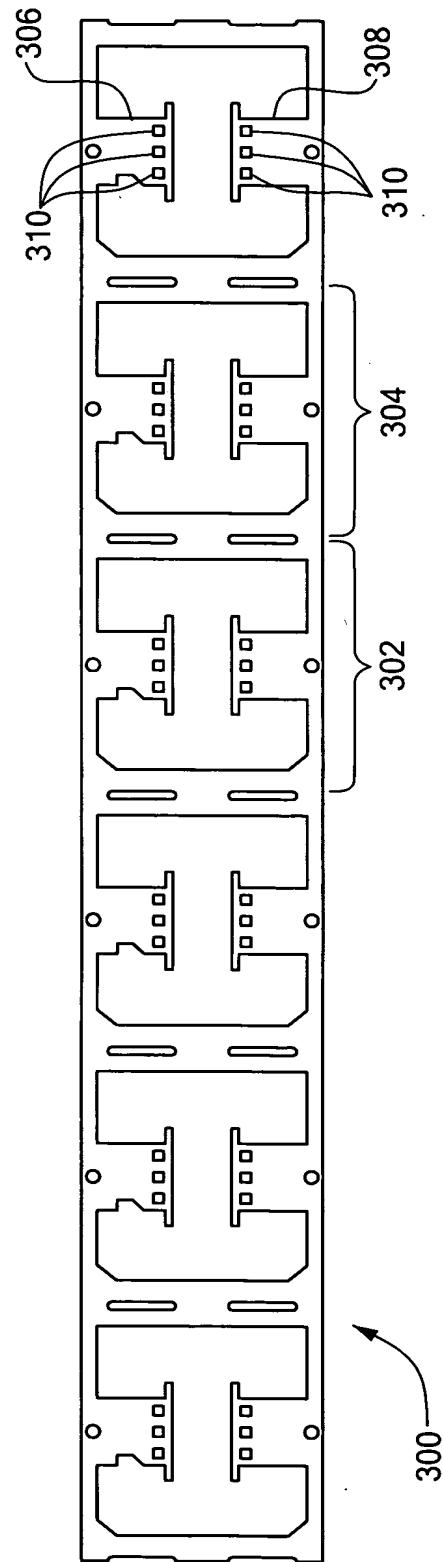


FIG. 3

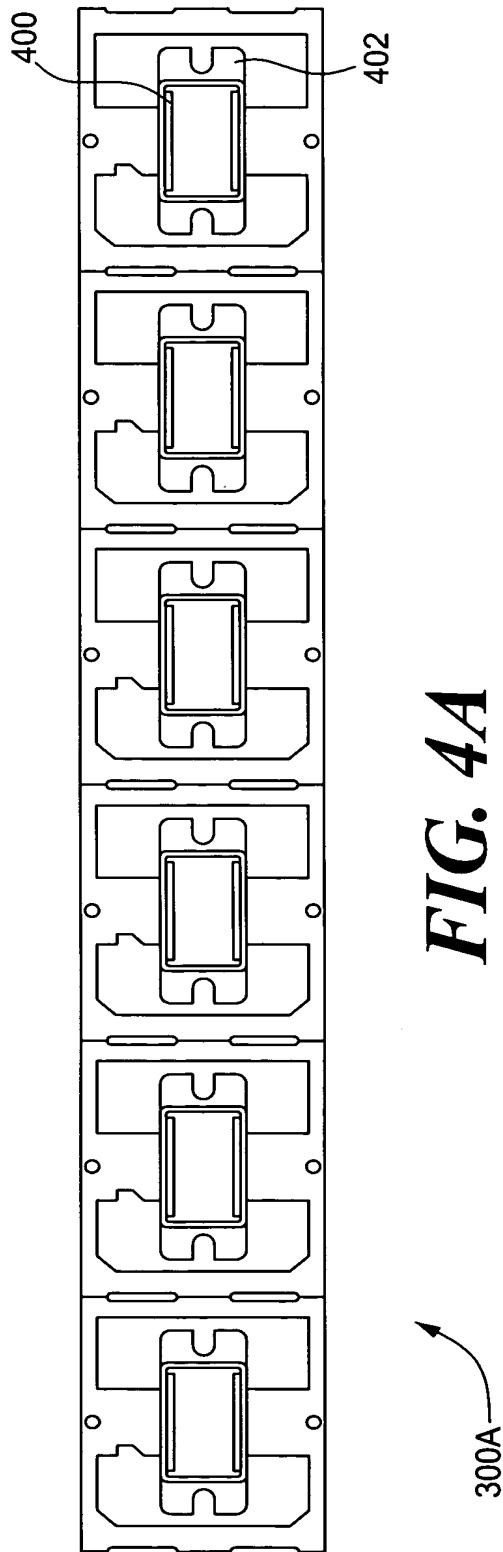


FIG. 4A

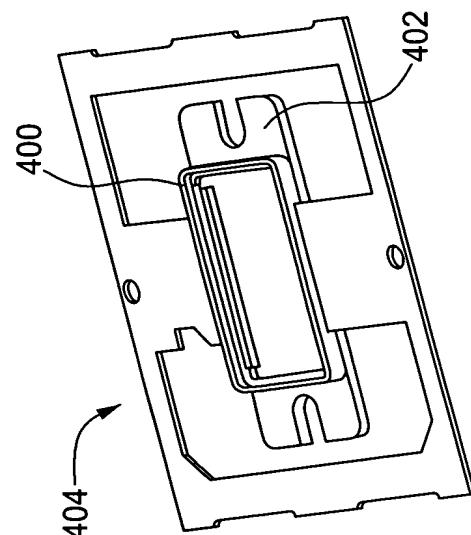
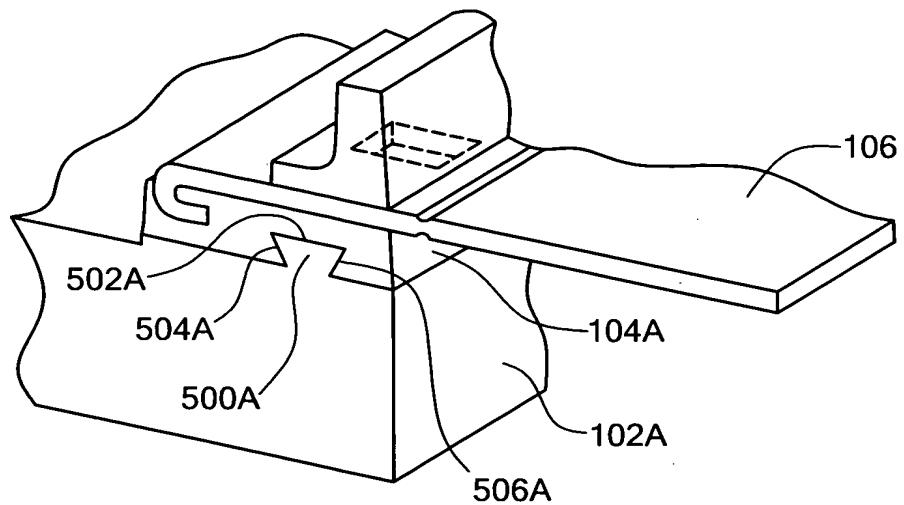
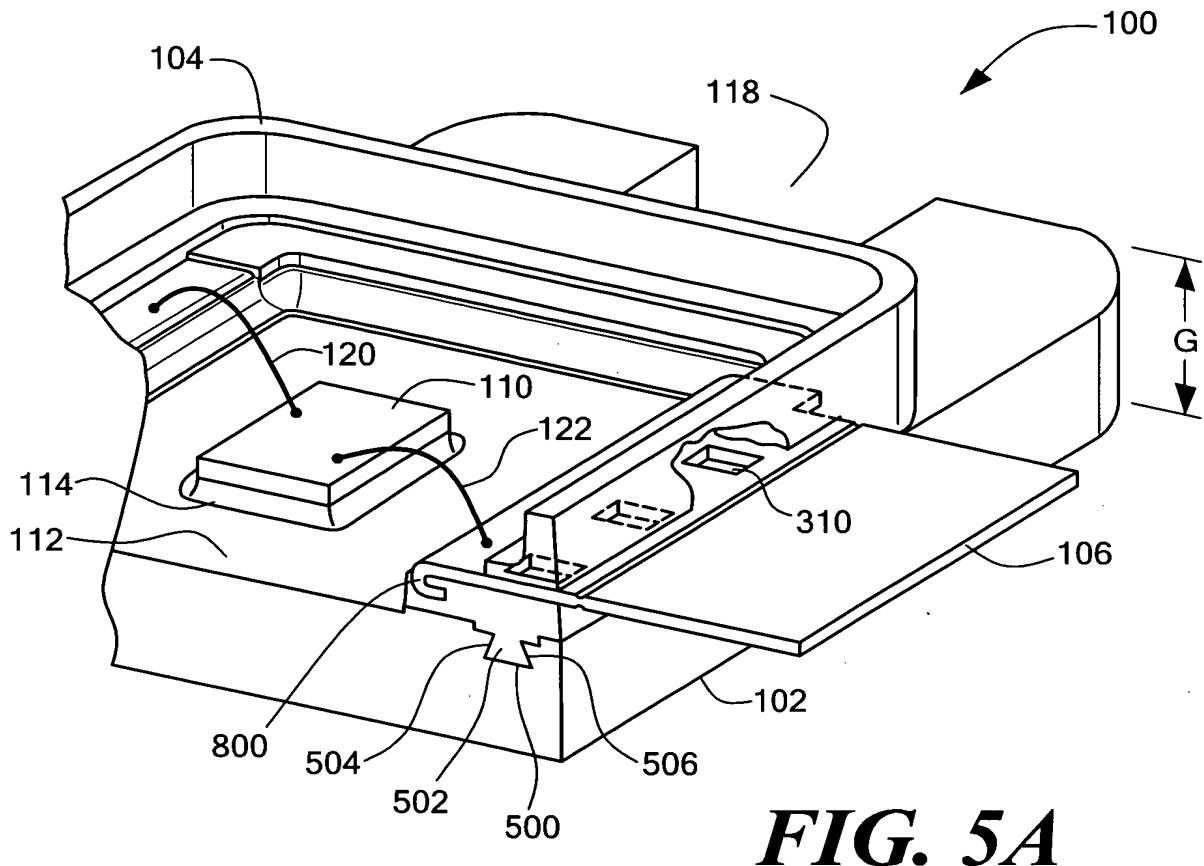


FIG. 4B

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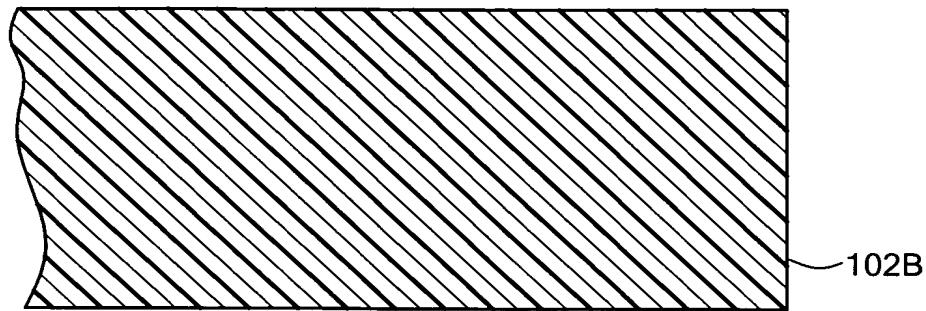


FIG. 6A

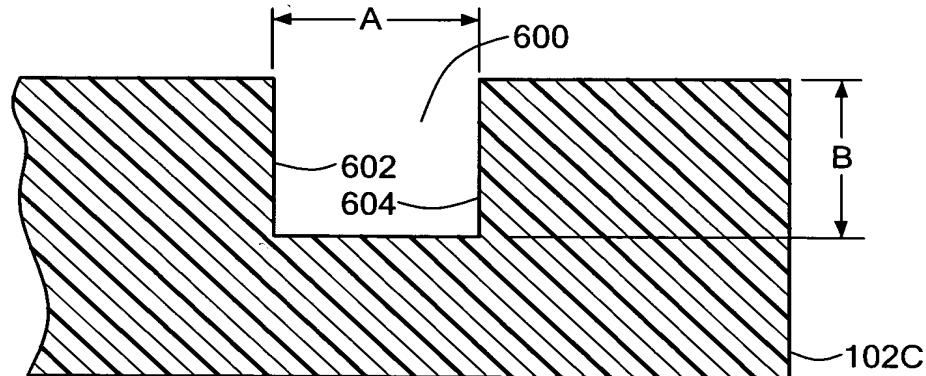


FIG. 6B

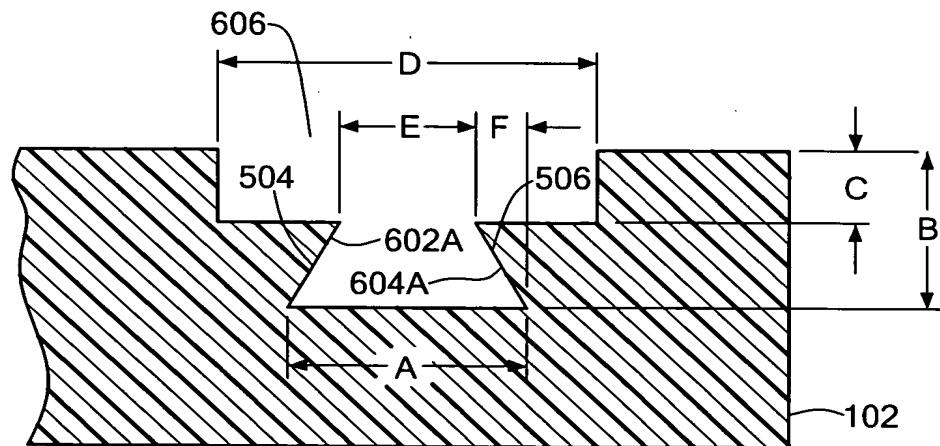


FIG 6C

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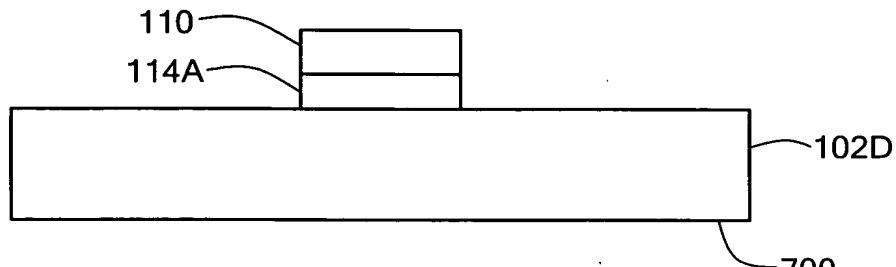


FIG. 7A

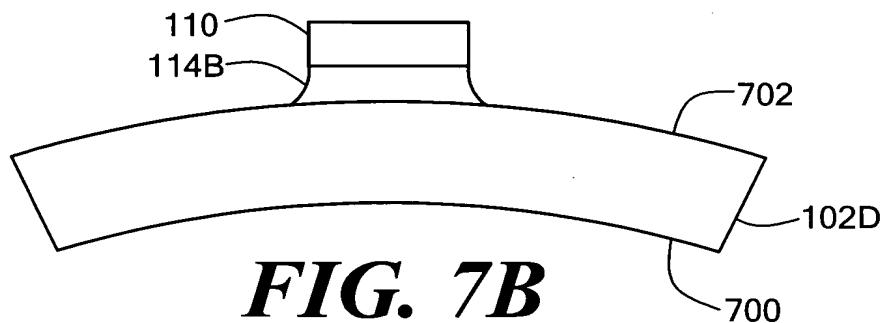


FIG. 7B

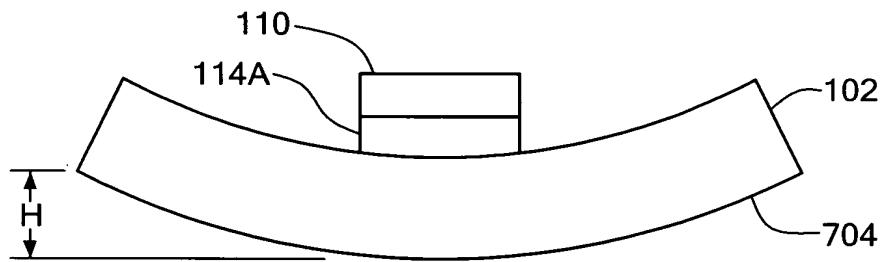


FIG. 7C

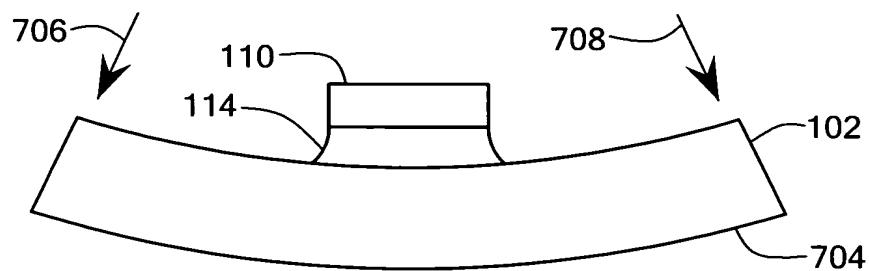


FIG 7D

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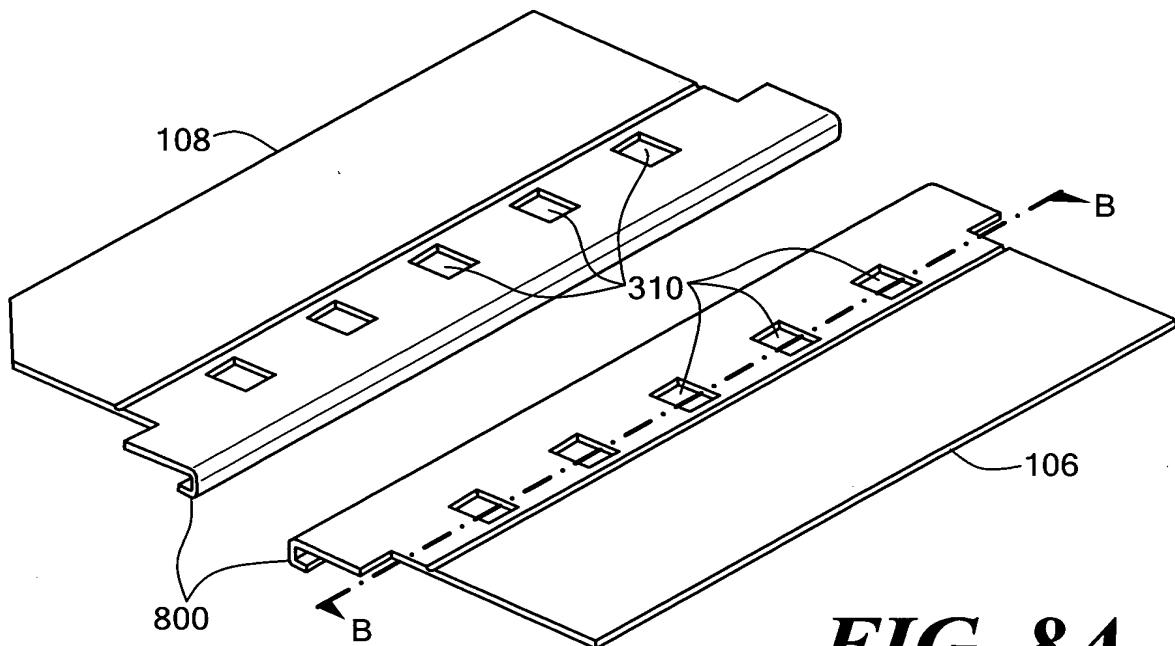


FIG. 8A

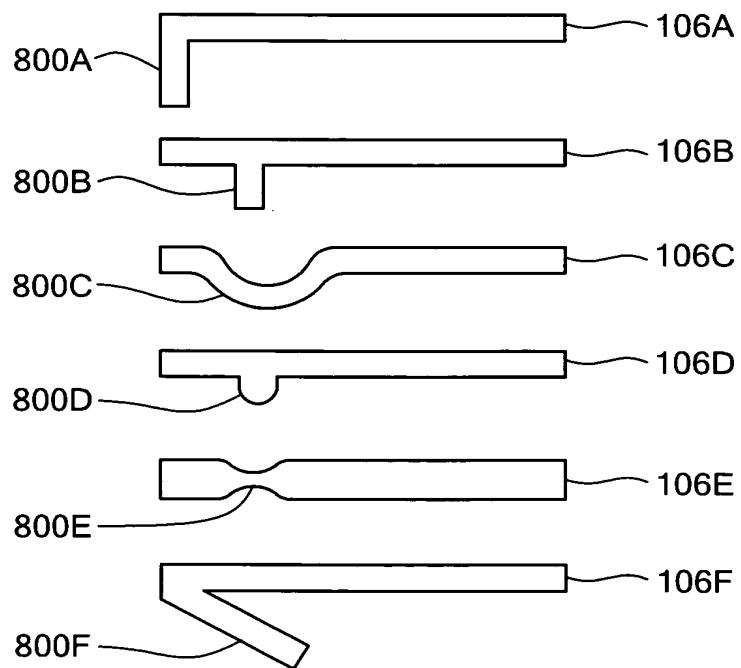


FIG. 8B

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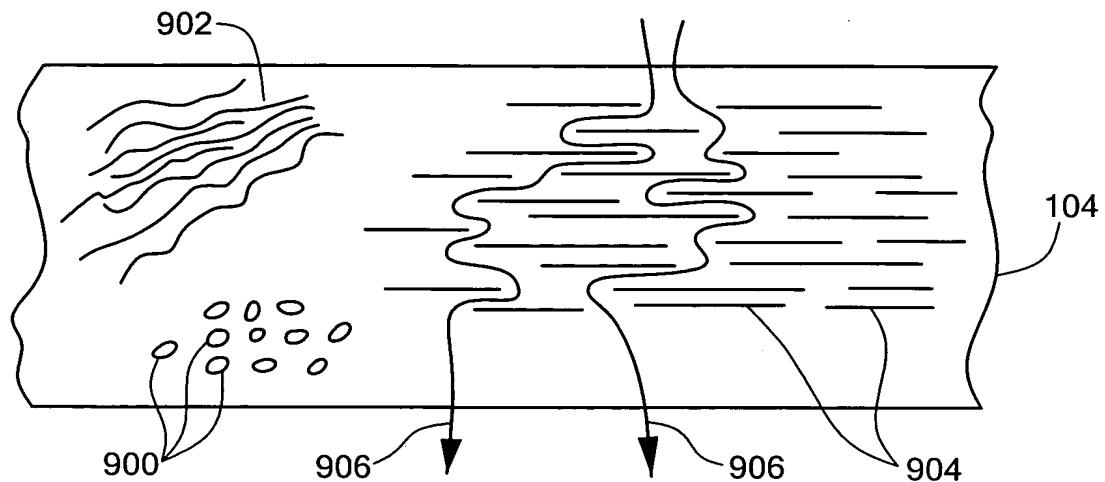
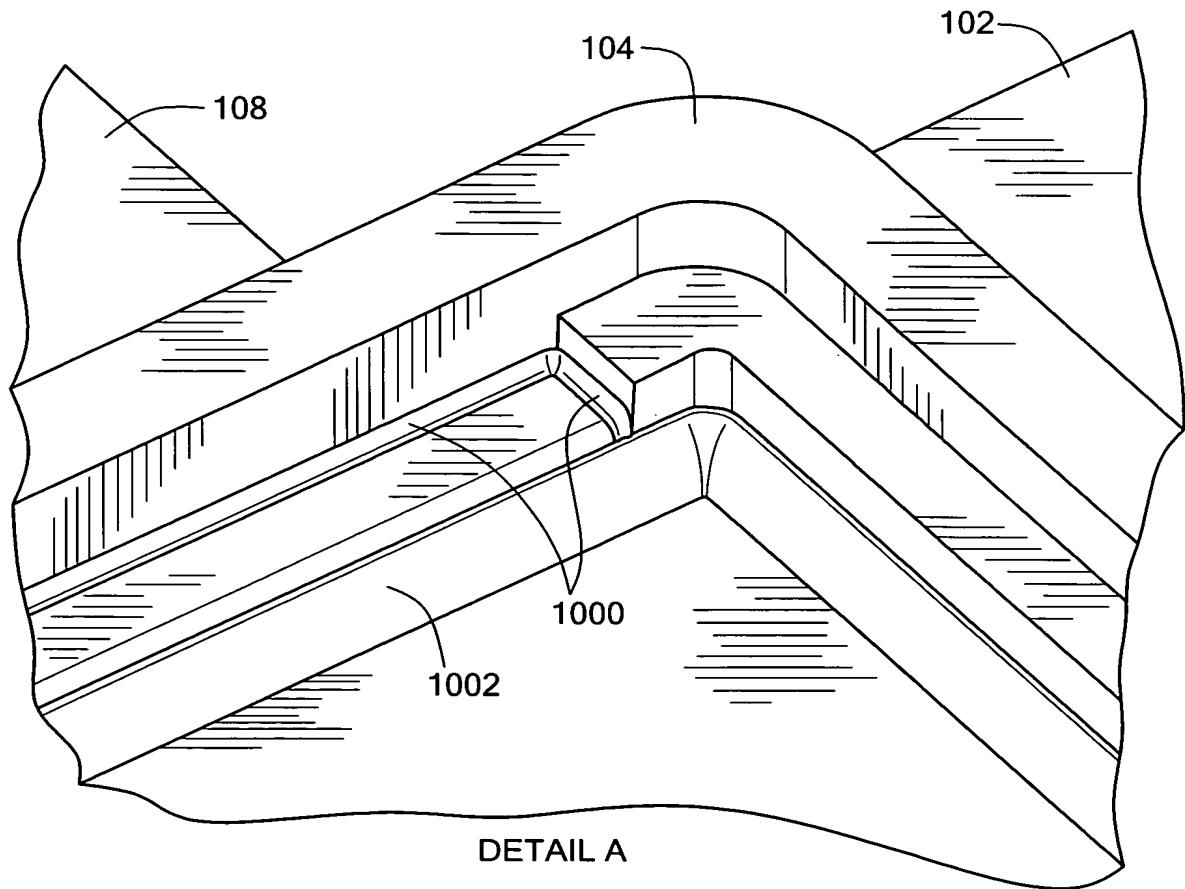


FIG. 9



DETAIL A

FIG. 10

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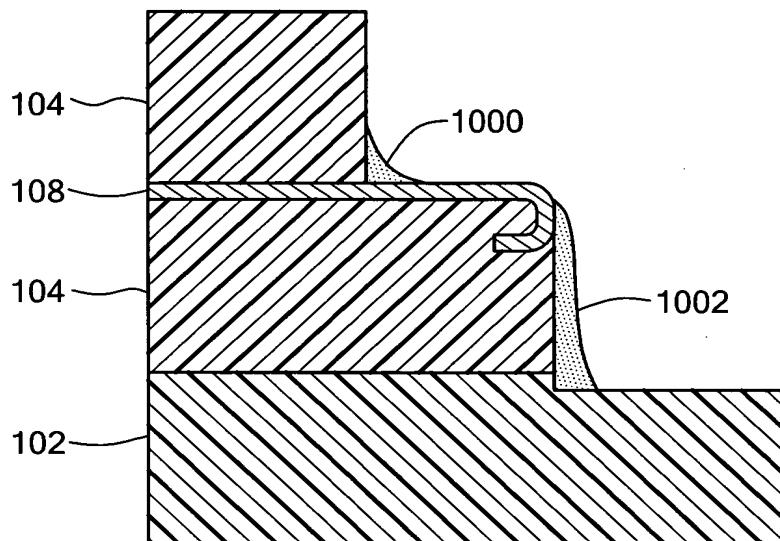


FIG. 11A

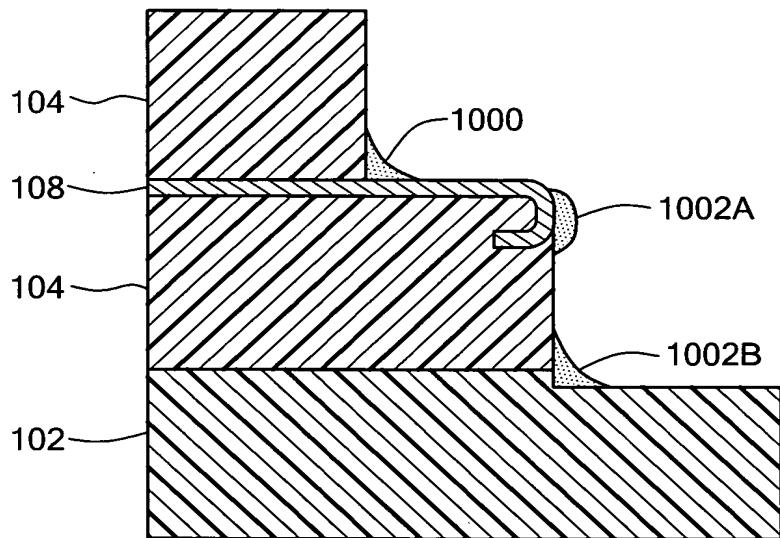


FIG 11B

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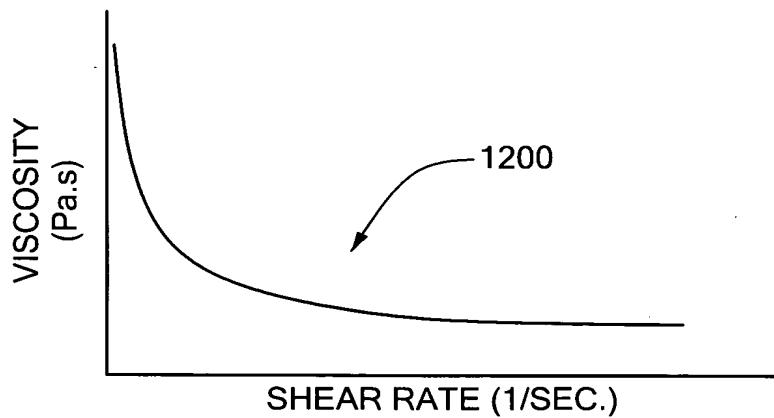


FIG. 12

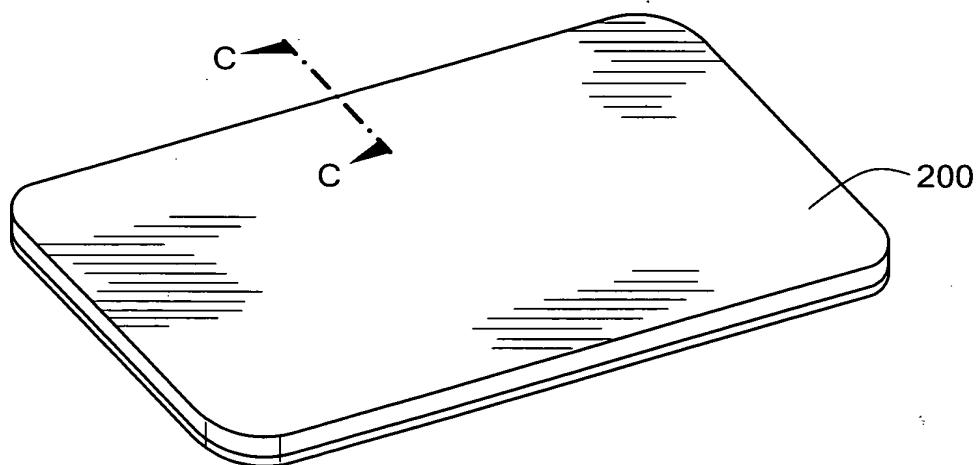


FIG. 13A

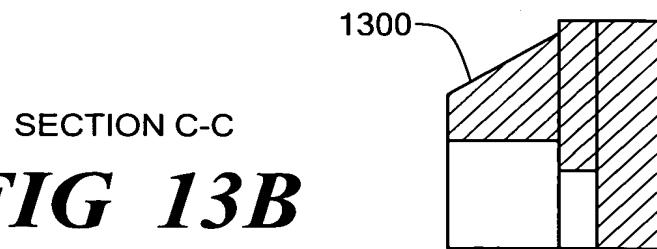


FIG. 13B

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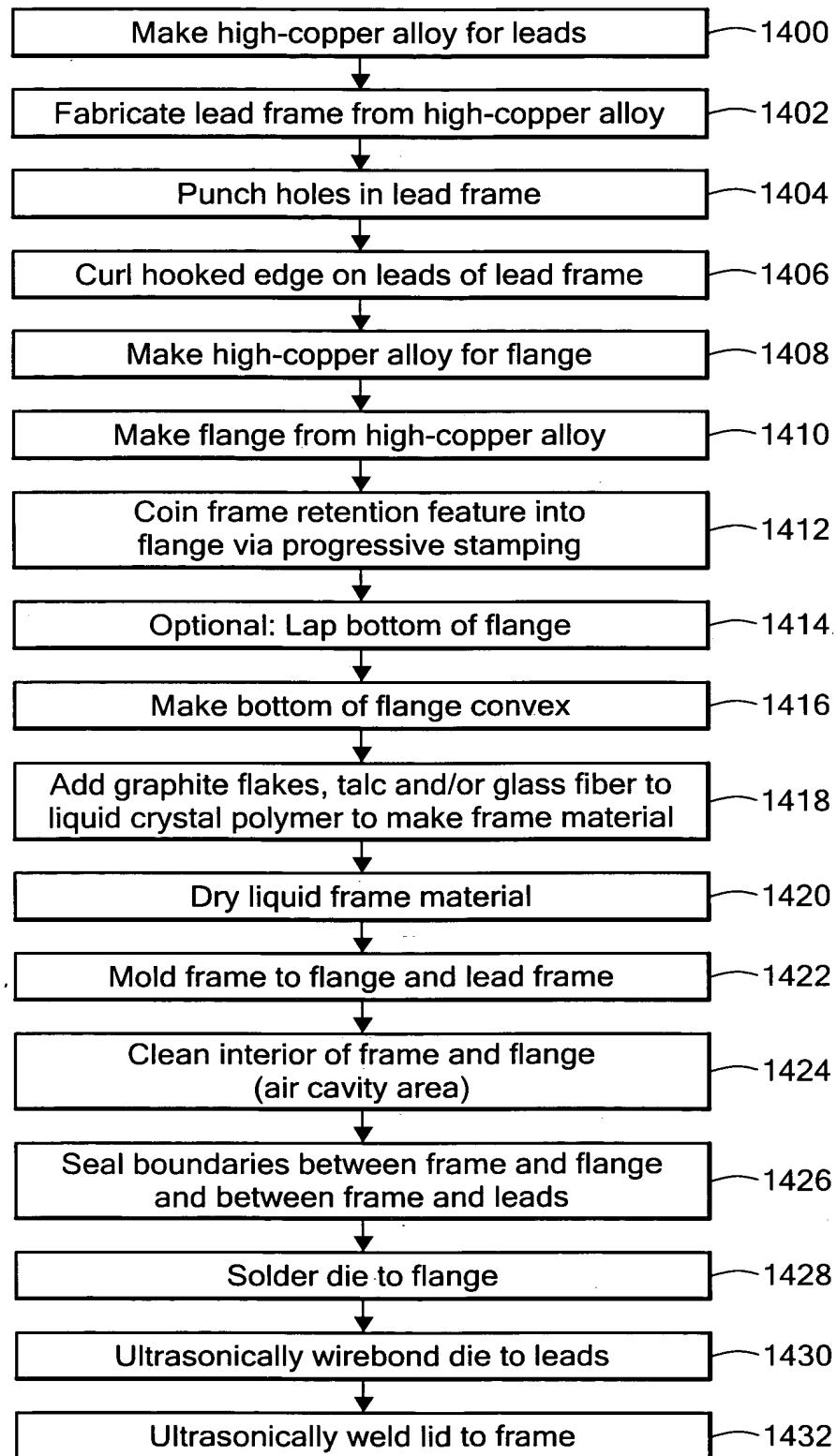


FIG 14